

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4640	liner and ((deposit\$3 or etch\$3 ) near3 (chamber or reactor or vessel or container))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 15:10
L2	361	1 and (acoustic or vibration)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 15:11
L3	2802	(acoustic or vibration) same liner	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 15:11
L4	15	3 and ((deposit\$3 or etch\$3 ) near3 (chamber or reactor or vessel or container))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 15:11
L15	2903	(quartz) with (exhaust or foreline or outlet)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/17 17:10
L16	321	15 same (particle or dust or contamination)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/17 17:11
S19	2421	(118/723e.ccls. or 118/723er.ccls. or 156/345.43-345.47.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S20	2624	141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S21	8181	137/262-264.ccls. or 137/454.2 or 137/560.ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07.ccls. or 137/602.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S22	498	261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05

S23	11276	118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S24	7369	261/64.1.ccls. or 261/65.ccls. or 261/75- 76.ccls. or 261/94-96. ccls. or 261/100-102. ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S25	31922	(118/715.ccls. or 118/728.ccls. or 118/50.ccls. or 156/345.29.ccls. or 156/345.33.ccls. or 156/345.34.ccls. or 156/345.35.ccls. or 156/345.36.ccls. or 156/345.26.ccls. or 156/345.51.ccls.) or (137/262-264.ccls. or 137/454.2 or 137/560. ccls. or 137/561r.ccls. or 137/561a.ccls. or 137/571-576.ccls. or 137/590.ccls. or 137/594-596.ccls. or 137/599.01.ccls. or 137/599.05-599.07. ccls. or 137/602.ccls.) or (141/285-286.ccls. or 141/37.ccls. or 141/44-47.ccls. or 141/54.ccls. or 141/301-302.ccls. or 141/367.ccls.) or (261/127.ccls. or 261/131.ccls. or 261/146-147.ccls. or 261/150.ccls.) or (261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42. ccls. or 261/62-63. ccls.) or (261/64.1. ccls. or 261/65.ccls. or 261/75-76.ccls. or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05

		261/94-96.ccls. or 261/100-102.ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.)				
S26	33688	S19 or S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S27	2656	261/19-22.ccls. or 261/23.1.ccls. or 261/40.ccls. or 261/42. ccls. or 261/62-63.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/29 09:05
S28	1	10/813543	US-PGPUB; USPAT	OR	ON	2008/03/07 13:45
S29	5	("4070638"   "5569502"   "6355561"   "6355561"   "6458416"   "6458416"   "6461436"   "6461436").PN.	US-PGPUB; USPAT	OR	ON	2008/03/07 14:11
S30	4	(acoustic adj driver) same liner	US-PGPUB; USPAT	OR	ON	2008/03/07 15:23
S31	963	(acoustic ) same liner	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:25
S32	180	S31 and (wafer or substrate or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:25
S33	501978	(acoustic or ultrason\$2 or ultrasound or infrason\$2 or infrasound or sonic or (sound adj wave))	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:51
S34	42218	(ALD or (atomic adj layer adj deposition))	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:52
S35	1316	S33 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:52
S36	81	S35 and liner	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:53
S37	1235	S35 not S36	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 15:57

S38	43	( "20010051440"   "20020022318"   "20020119245"   "20050000942"   "20050263489"   "20050279381"   "20060270242"   "20070051700"   "4446115"   "5017513"   "5022961"   "5277835"   "5326429"   "5391511"   "5472513"   "5487398"   "5650041"   "5681398"   "5800632"   "5837662"   "5981454"   "6010927"   "6074961"   "6127282"   "6129091"   "6174818"   "6200896"   "6207565"   "6235693"   "6245650"   "6315913"   "6329299"   "6453914"   "6562726"   "6589882"   "6627548"   "6683007"   "6783694"   "6830628"   "6893893"   "6936544"   "6984585"   "7008837").PN. OR ("7320942").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/07 16:40
S39	2	10/285967	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/07 16:43
S40	209	S35 not S36	USPAT	OR	ON	2008/03/07 16:49
S41	17	( "20010010614"   "20030076095"   "20030077843"   "20040043620"   "4760481"   "5198380"   "5221417"   "5726480"   "6076252"   "6154346"   "6233813"   "6296776"   "6330743"   "6391216"   "6395639"   "6452742").PN. OR ("7105361").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/07 16:57
S42	4975	(118/715,723e).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/03/07 17:19

S43	256	S33 and S42	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/07 17:20
S44	15	("4190015"   "4313783"   "4807561"   "4827867"   "5180431"   "5250114"   "5250116"   "5449405"   "5489337"   "5695817"   "5769946"   "5939130"   "5985357"   "6190063").PN. OR ("6416579").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/07 17:36
S45	38849	"0" "425" "419"	EPO	OR	ON	2008/03/07 18:02
S46	0	"0425419"	EPO	OR	ON	2008/03/07 18:03
S47	2	((("5387777") or ("5367139")).PN.	US-PGPUB; USPAT	OR	OFF	2008/03/07 18:04
S48	736	quartz with liner	US-PGPUB; USPAT	OR	ON	2008/03/07 18:12
S49	345	S48 and plasma	US-PGPUB; USPAT	OR	ON	2008/03/07 18:13
S50	326	S49 and (wafer or substrate or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 18:13
S51	264	S50 and (contamination or dust or particle or dirt)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/07 18:14
S52	1	10/453394	US-PGPUB; USPAT	OR	ON	2008/03/08 22:28
S53	2	Gealy-F-Dan.in.	US-PGPUB; USPAT	OR	ON	2008/03/08 22:38
S54	341	Basceri-Cem.in.	US-PGPUB; USPAT	OR	ON	2008/03/08 22:38
S55	341	S53 S54	US-PGPUB; USPAT	OR	ON	2008/03/08 22:38
S56	2	S55 and acoustic	US-PGPUB; USPAT	OR	ON	2008/03/08 22:49
S61	262	"SiF.sub.4" with precursor	US-PGPUB; USPAT	OR	ON	2008/03/09 08:46
S62	455	(freon or "CF.sub.4" or "CCl.sub.2F.sub.2" or "NF.sub.3") with precursor	US-PGPUB; USPAT	OR	ON	2008/03/09 08:58
S63	66	S61 and S62	US-PGPUB; USPAT	OR	ON	2008/03/09 08:58

S64	241	(acoustic or ultrason\$2 or ultrasound or infrason\$2 or infrasound or sonic or (sound adj wave)) with apodiz\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 11:44
S65	49	S64 and (hz or khz)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 11:50
S66	140	S64 and (wafer or substrate or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:01
S67	36	S66 and (hz or khz)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:01
S68	23	S65 and (etch\$3 or deposit\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:01
S69	13	S68 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:45
S70	7	S64 and (semiconductor adj ( process\$3 or product \$3 or manufactur\$3 or treat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:48
S71	154	apodiz\$3 and (semiconductor adj ( process\$3 or product \$3 or manufactur\$3 or treat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:50
S72	86	(acoustic or ultrason\$2 or ultrasound or infrason\$2 or infrasound or sonic or (sound adj wave)) and S71	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 12:51
S73	1	("4,518,889").PN.	US-PGPUB; USPAT	OR	OFF	2008/03/09 15:13
S74	15	(quartz near3 liner) with (exhaust or foreline or outlet)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 15:49
S75	3	liner with foreline	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2008/03/09 16:33
S76	1	("5,798,016").PN.	US-PGPUB; USPAT	OR	OFF	2008/03/09 17:18
S77	1727	(acoustic or vibration) with liner	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:22

S78	394	S77 and (wafer or substrate or article or workpiece)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:23
S79	228	S78 and (chamber or reactor or vessel or container)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:26
S80	2802	(acoustic or vibration) same liner	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:39
S81	1075	S80 not S77	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:39
S82	3	S81 and ((deposit\$3 or etch\$3) near3 (chamber or reactor or vessel or container))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2008/03/17 13:40

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